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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

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Details

Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	20 MIPS
Connectivity	CANbus, I ² C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24hj128gp504-h-pt

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name	Pin Type	Buffer Type	PPS	Description
AN0-AN12	I	Analog		Analog input channels.
CLKI	I	ST/CMOS	No	External clock source input. Always associated with OSC1 pin function. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLK0 in RC and EC modes.
CLKO	O	—	No	Always associated with OSC2 pin function.
OSC1	I	ST/CMOS	No	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	I/O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLK0 in RC and EC modes.
SOSCI	I	ST/CMOS	No	32.768 kHz low-power oscillator crystal input; CMOS otherwise.
SOSCO	O	—	No	32.768 kHz low-power oscillator crystal output.
CN0-CN30	I	ST	No	Change notification inputs. Can be software programmed for internal weak pull-ups on all inputs.
IC1-IC2	I	ST	Yes	Capture inputs 1/2
IC7-IC8	I	ST	Yes	Capture inputs 7/8.
OCFA	I	ST	Yes	Compare Fault A input (for Compare Channels 1, 2, 3 and 4).
OC1-OC4	O	—	Yes	Compare outputs 1 through 4.
INT0	I	ST	No	External interrupt 0.
INT1	I	ST	Yes	External interrupt 1.
INT2	I	ST	Yes	External interrupt 2.
RA0-RA4	I/O	ST	No	PORTA is a bidirectional I/O port.
RA7-RA10	I/O	ST	No	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	No	PORTB is a bidirectional I/O port.
RC0-RC9	I/O	ST	No	PORTC is a bidirectional I/O port.
T1CK	I	ST	No	Timer1 external clock input.
T2CK	I	ST	Yes	Timer2 external clock input.
T3CK	I	ST	Yes	Timer3 external clock input.
T4CK	I	ST	Yes	Timer4 external clock input.
T5CK	I	ST	Yes	Timer5 external clock input.
$\overline{\text{U1CTS}}$	I	ST	Yes	UART1 clear to send.
U1RTS	O	—	Yes	UART1 ready to send.
U1RX	I	ST	Yes	UART1 receive.
U1TX	O	—	Yes	UART1 transmit.
$\overline{\text{U2CTS}}$	I	ST	Yes	UART2 clear to send.
U2RTS	O	—	Yes	UART2 ready to send.
U2RX	I	ST	Yes	UART2 receive.
U2TX	O	—	Yes	UART2 transmit.
SCK1	I/O	ST	Yes	Synchronous serial clock input/output for SPI1.
SDI1	I	ST	Yes	SPI1 data in.
SDO1	O	—	Yes	SPI1 data out.
SS1	I/O	ST	Yes	SPI1 slave synchronization or frame pulse I/O.
SCK2	I/O	ST	Yes	Synchronous serial clock input/output for SPI2.
SDI2	I	ST	Yes	SPI2 data in.
SDO2	O	—	Yes	SPI2 data out.
SS2	I/O	ST	Yes	SPI2 slave synchronization or frame pulse I/O.

Legend: CMOS = CMOS compatible input or output Analog = Analog input P = Power
ST = Schmitt Trigger input with CMOS levels O = Output I = Input
PPS = Peripheral Pin Select TTL = TTL input buffer

4.1.1 PROGRAM MEMORY ORGANIZATION

The program memory space is organized in word-addressable blocks. Although it is treated as 24 bits wide, it is more appropriate to think of each address of the program memory as a lower and upper word, with the upper byte of the upper word being unimplemented. The lower word always has an even address, while the upper word has an odd address, as shown in [Figure 4-2](#).

Program memory addresses are always word-aligned on the lower word, and addresses are incremented or decremented by two during code execution. This arrangement provides compatibility with data memory space addressing and makes data in the program memory space accessible.

4.1.2 INTERRUPT AND TRAP VECTORS

All PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 devices reserve the addresses between 0x00000 and 0x000200 for hard-coded program execution vectors. A hardware Reset vector is provided to redirect code execution from the default value of the PC on device Reset to the actual start of code. A GOTO instruction is programmed by the user application at 0x000000, with the actual address for the start of code at 0x000002.

PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 devices also have two interrupt vector tables, located from 0x000004 to 0x0000FF and 0x000100 to 0x0001FF. These vector tables allow each of the device interrupt sources to be handled by separate Interrupt Service Routines (ISRs). A more detailed discussion of the interrupt vector tables is provided in [Section 7.1 “Interrupt Vector Table”](#).

FIGURE 4-2: PROGRAM MEMORY ORGANIZATION

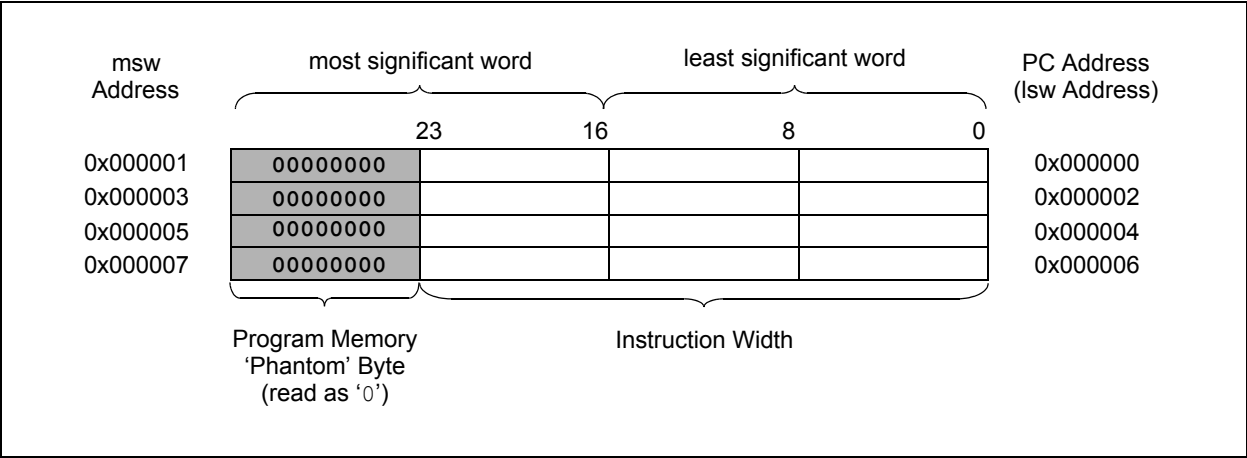


TABLE 4-18: ECAN1 REGISTER MAP WHEN C1CTRL1.WIN = 1 (FOR PIC24HJ128GP502/504 AND PIC24HJ64GP502/504)

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets		
	0400-041E	See definition when WIN = x																		
C1BUFPNT1	0420	F3BP<3:0>				F2BP<3:0>				F1BP<3:0>				F0BP<3:0>				0000		
C1BUFPNT2	0422	F7BP<3:0>				F6BP<3:0>				F5BP<3:0>				F4BP<3:0>				0000		
C1BUFPNT3	0424	F11BP<3:0>				F10BP<3:0>				F9BP<3:0>				F8BP<3:0>				0000		
C1BUFPNT4	0426	F15BP<3:0>				F14BP<3:0>				F13BP<3:0>				F12BP<3:0>				0000		
C1RXM0SID	0430	SID<10:3>								SID<2:0>		—	MIDE	—	EID<17:16>			xxxx		
C1RXM0EID	0432	EID<15:8>								EID<7:0>								xxxx		
C1RXM1SID	0434	SID<10:3>								SID<2:0>		—	MIDE	—	EID<17:16>			xxxx		
C1RXM1EID	0436	EID<15:8>								EID<7:0>								xxxx		
C1RXM2SID	0438	SID<10:3>								SID<2:0>		—	MIDE	—	EID<17:16>			xxxx		
C1RXM2EID	043A	EID<15:8>								EID<7:0>								xxxx		
C1RXF0SID	0440	SID<10:3>								SID<2:0>		—	EXIDE	—	EID<17:16>			xxxx		
C1RXF0EID	0442	EID<15:8>								EID<7:0>								xxxx		
C1RXF1SID	0444	SID<10:3>								SID<2:0>		—	EXIDE	—	EID<17:16>			xxxx		
C1RXF1EID	0446	EID<15:8>								EID<7:0>								xxxx		
C1RXF2SID	0448	SID<10:3>								SID<2:0>		—	EXIDE	—	EID<17:16>			xxxx		
C1RXF2EID	044A	EID<15:8>								EID<7:0>								xxxx		
C1RXF3SID	044C	SID<10:3>								SID<2:0>		—	EXIDE	—	EID<17:16>			xxxx		
C1RXF3EID	044E	EID<15:8>								EID<7:0>								xxxx		
C1RXF4SID	0450	SID<10:3>								SID<2:0>		—	EXIDE	—	EID<17:16>			xxxx		
C1RXF4EID	0452	EID<15:8>								EID<7:0>								xxxx		
C1RXF5SID	0454	SID<10:3>								SID<2:0>		—	EXIDE	—	EID<17:16>			xxxx		
C1RXF5EID	0456	EID<15:8>								EID<7:0>								xxxx		
C1RXF6SID	0458	SID<10:3>								SID<2:0>		—	EXIDE	—	EID<17:16>			xxxx		
C1RXF6EID	045A	EID<15:8>								EID<7:0>								xxxx		
C1RXF7SID	045C	SID<10:3>								SID<2:0>		—	EXIDE	—	EID<17:16>			xxxx		
C1RXF7EID	045E	EID<15:8>								EID<7:0>								xxxx		
C1RXF8SID	0460	SID<10:3>								SID<2:0>		—	EXIDE	—	EID<17:16>			xxxx		
C1RXF8EID	0462	EID<15:8>								EID<7:0>								xxxx		
C1RXF9SID	0464	SID<10:3>								SID<2:0>		—	EXIDE	—	EID<17:16>			xxxx		
C1RXF9EID	0466	EID<15:8>								EID<7:0>								xxxx		
C1RXF10SID	0468	SID<10:3>								SID<2:0>		—	EXIDE	—	EID<17:16>			xxxx		
C1RXF10EID	046A	EID<15:8>								EID<7:0>								xxxx		

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

9.0 OSCILLATOR CONFIGURATION

Note 1: This data sheet summarizes the features of the PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 39. "Oscillator (Part III)"** (DS70216) of the "dsPIC33F/PIC24H Family Reference Manual", which is available from the Microchip website (www.microchip.com).

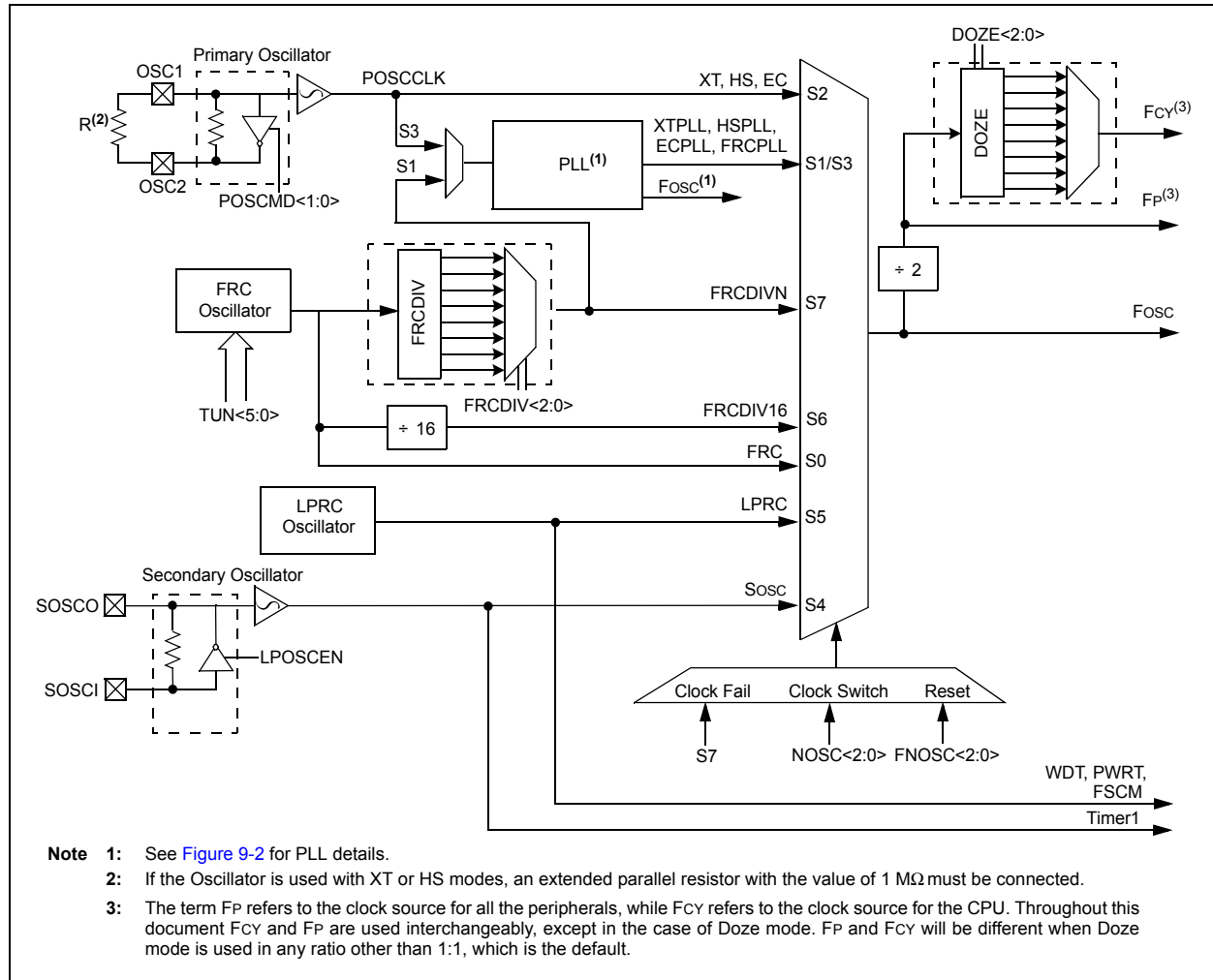
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 oscillator system provides:

- External and internal oscillator options as clock sources
- An on-chip Phase-Locked Loop (PLL) to scale the internal operating frequency to the required system clock frequency
- An internal FRC oscillator that can also be used with the PLL, thereby allowing full-speed operation without any external clock generation hardware
- Clock switching between various clock sources
- Programmable clock postscaler for system power savings
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and takes fail-safe measures
- An Oscillator Control register (OSCCON)
- Nonvolatile Configuration bits for main oscillator selection.

A simplified diagram of the oscillator system is shown in **Figure 9-1**.

FIGURE 9-1: OSCILLATOR SYSTEM DIAGRAM



10.5 Power-Saving Resources

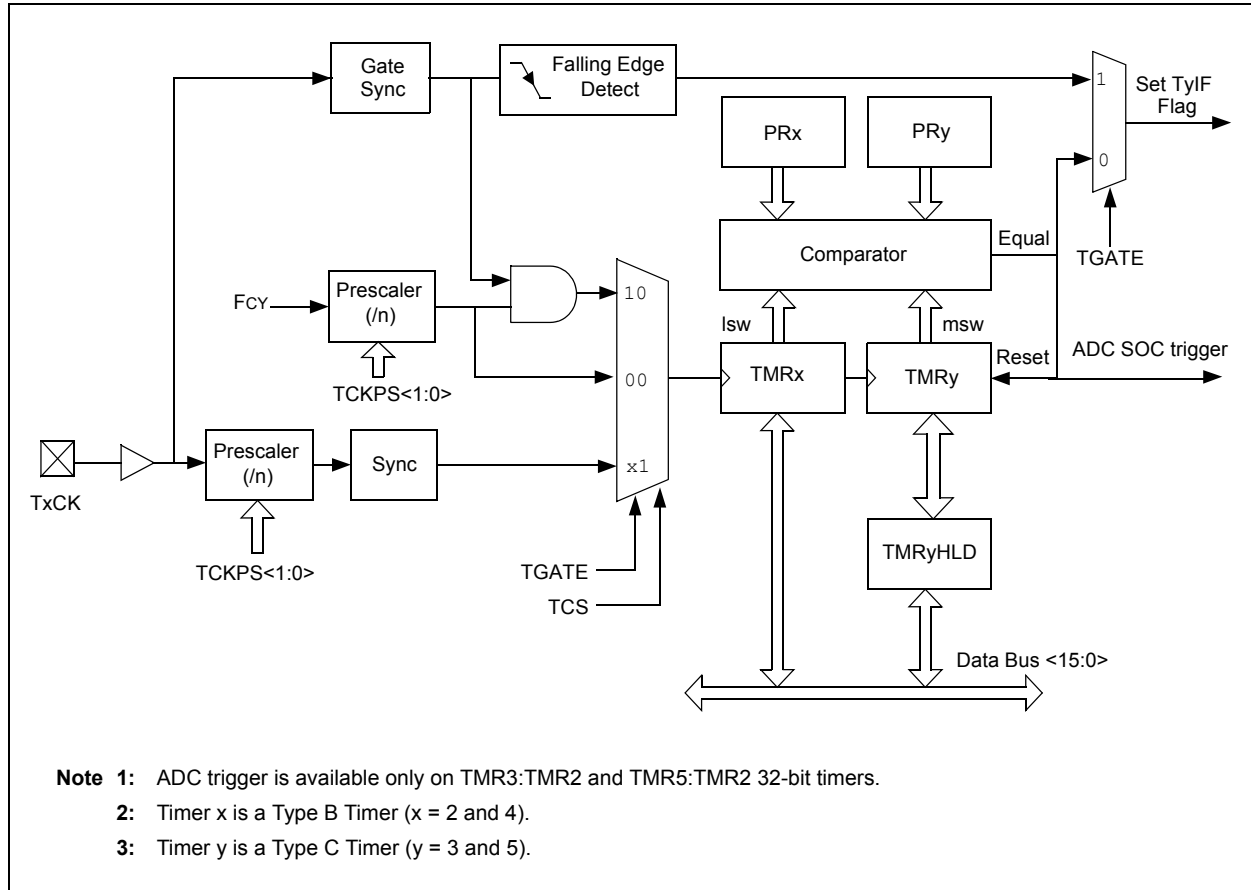
Many useful resources related to power-saving modes are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this [link](http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532315), contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532315
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10.5.1 KEY RESOURCES

- **Section 9. “Watchdog Timer and Power-Saving Modes”** (DS70196)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

FIGURE 13-3: 32-BIT TIMER BLOCK DIAGRAM



13.3 Timer Resources

Many useful resources related to Timers are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this [link](http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532315), contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532315>

13.3.1 KEY RESOURCES

- **Section 11. “Timers”** (DS70205)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

REGISTER 13-2: TxCON: TIMER CONTROL REGISTER (x = 3 OR 5)

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON ⁽²⁾	—	TSIDL ⁽¹⁾	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	U-0
—	TGATE ⁽²⁾	TCKPS<1:0> ⁽²⁾		—	—	TCS ⁽²⁾	—
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15 **TON:** Timery On bit⁽²⁾
1 = Starts 16-bit Timerx
0 = Stops 16-bit Timerx
- bit 14 **Unimplemented:** Read as '0'
- bit 13 **TSIDL:** Stop in Idle Mode bit⁽¹⁾
1 = Discontinue timer operation when device enters Idle mode
0 = Continue timer operation in Idle mode
- bit 12-7 **Unimplemented:** Read as '0'
- bit 6 **TGATE:** Timerx Gated Time Accumulation Enable bit⁽²⁾
When TCS = 1:
This bit is ignored.
When TCS = 0:
1 = Gated time accumulation enabled
0 = Gated time accumulation disabled
- bit 5-4 **TCKPS<1:0>:** Timerx Input Clock Prescale Select bits⁽²⁾
11 = 1:256 prescale value
10 = 1:64 prescale value
01 = 1:8 prescale value
00 = 1:1 prescale value
- bit 3-2 **Unimplemented:** Read as '0'
- bit 1 **TCS:** Timerx Clock Source Select bit⁽²⁾
1 = External clock from TxCK pin
0 = Internal clock (Fosc/2)
- bit 0 **Unimplemented:** Read as '0'

Note 1: When 32-bit timer operation is enabled (T32 = 1) in the Timer Control register (TxCON<3>), the TSIDL bit must be cleared to operate the 32-bit timer in Idle mode.

2: When the 32-bit timer operation is enabled (T32 = 1) in the Timer Control register (TxCON<3>), these bits have no effect.

14.1 Input Capture Resources

Many useful resources related to Input Capture are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this [link](http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532315), contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532315
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14.1.1 KEY RESOURCES

- **Section 12. “Input Capture”** (DS70198)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

REGISTER 18-1: UxMODE: UARTx MODE REGISTER (CONTINUED)

bit 4	URXINV: Receive Polarity Inversion bit 1 = UxRX Idle state is '0' 0 = UxRX Idle state is '1'
bit 3	BRGH: High Baud Rate Enable bit 1 = BRG generates 4 clocks per bit period (4x baud clock, High-Speed mode) 0 = BRG generates 16 clocks per bit period (16x baud clock, Standard mode)
bit 2-1	PDSEL<1:0>: Parity and Data Selection bits 11 = 9-bit data, no parity 10 = 8-bit data, odd parity 01 = 8-bit data, even parity 00 = 8-bit data, no parity
bit 0	STSEL: Stop Bit Selection bit 1 = Two Stop bits 0 = One Stop bit

- Note 1:** Refer to **Section 17. "UART"** (DS70232) in the *"dsPIC33F/PIC24H Family Reference Manual"* for information on enabling the UART module for receive or transmit operation.
- 2:** This feature is only available for the 16x BRG mode (BRGH = 0).

REGISTER 19-22: CIRXFUL1: ECAN™ RECEIVE BUFFER FULL REGISTER 1

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL15	RXFUL14	RXFUL13	RXFUL12	RXFUL11	RXFUL10	RXFUL9	RXFUL8
bit 15						bit 8	

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL7	RXFUL6	RXFUL5	RXFUL4	RXFUL3	RXFUL2	RXFUL1	RXFUL0
bit 7						bit 0	

Legend: C = Writeable bit, but only '0' can be written to clear the bit
R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **RXFUL<15:0>:** Receive Buffer n Full bits
1 = Buffer is full (set by module)
0 = Buffer is empty

REGISTER 19-23: CIRXFUL2: ECAN™ RECEIVE BUFFER FULL REGISTER 2

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL31	RXFUL30	RXFUL29	RXFUL28	RXFUL27	RXFUL26	RXFUL25	RXFUL24
bit 15						bit 8	

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL23	RXFUL22	RXFUL21	RXFUL20	RXFUL19	RXFUL18	RXFUL17	RXFUL16
bit 7						bit 0	

Legend: C = Writeable bit, but only '0' can be written to clear the bit
R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 15-0 **RXFUL<31:16>:** Receive Buffer n Full bits
1 = Buffer is full (set by module)
0 = Buffer is empty

PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 AND PIC24HJ128GPX02/X04

BUFFER 19-3: ECAN™ MESSAGE BUFFER WORD 2

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID5	EID4	EID3	EID2	EID1	EID0	RTR	RB1
bit 15							bit 8

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	RB0	DLC3	DLC2	DLC1	DLC0
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15-10 **EID<5:0>**: Extended Identifier bits
- bit 9 **RTR**: Remote Transmission Request bit
1 = Message will request remote transmission
0 = Normal message
- bit 8 **RB1**: Reserved Bit 1
User must set this bit to '0' per CAN protocol.
- bit 7-5 **Unimplemented**: Read as '0'
- bit 4 **RB0**: Reserved Bit 0
User must set this bit to '0' per CAN protocol.
- bit 3-0 **DLC<3:0>**: Data Length Code bits

BUFFER 19-4: ECAN™ MESSAGE BUFFER WORD 3

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 1							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 0							
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 15-8 **Byte 1<15:8>**: ECAN™ Message Byte 0
- bit 7-0 **Byte 0<7:0>**: ECAN Message Byte 1

21.2 Comparator Control Register

REGISTER 21-1: CMCON: COMPARATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CMIDL	—	C2EVT	C1EVT	C2EN	C1EN	C2OUTEN ⁽¹⁾	C1OUTEN ⁽²⁾
bit 15							bit 8

R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
C2OUT	C1OUT	C2INV	C1INV	C2NEG	C2POS	C1NEG	C1POS
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

- bit 15 **CMIDL:** Stop in Idle Mode
 1 = When device enters Idle mode, module does not generate interrupts. Module is still enabled
 0 = Continue normal module operation in Idle mode
- bit 14 **Unimplemented:** Read as '0'
- bit 13 **C2EVT:** Comparator 2 Event
 1 = Comparator output changed states
 0 = Comparator output did not change states
- bit 12 **C1EVT:** Comparator 1 Event
 1 = Comparator output changed states
 0 = Comparator output did not change states
- bit 11 **C2EN:** Comparator 2 Enable
 1 = Comparator is enabled
 0 = Comparator is disabled
- bit 10 **C1EN:** Comparator 1 Enable
 1 = Comparator is enabled
 0 = Comparator is disabled
- bit 9 **C2OUTEN:** Comparator 2 Output Enable⁽¹⁾
 1 = Comparator output is driven on the output pad
 0 = Comparator output is not driven on the output pad
- bit 8 **C1OUTEN:** Comparator 1 Output Enable⁽²⁾
 1 = Comparator output is driven on the output pad
 0 = Comparator output is not driven on the output pad
- bit 7 **C2OUT:** Comparator 2 Output bit
 When C2INV = 0:
 1 = C2 VIN+ > C2 VIN-
 0 = C2 VIN+ < C2 VIN-
 When C2INV = 1:
 0 = C2 VIN+ > C2 VIN-
 1 = C2 VIN+ < C2 VIN-

Note 1: If C2OUTEN = 1, the C2OUT peripheral output must be configured to an available RPx pin. See [Section 11.6 “Peripheral Pin Select”](#) for more information.

2: If C1OUTEN = 1, the C1OUT peripheral output must be configured to an available RPx pin. See [Section 11.6 “Peripheral Pin Select”](#) for more information.

TABLE 25-3: CODE FLASH SECURITY SEGMENT SIZES FOR 32 KB DEVICES

CONFIG BITS	BSS<2:0> = x11 0K		BSS<2:0> = x10 1K		BSS<2:0> = x01 4K		BSS<2:0> = x00 8K	
SSS<2:0> = x11 0K	VS = 256 IW	0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x0057FEh	VS = 256 IW	0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x0057FEh	VS = 256 IW	0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x0057FEh	VS = 256 IW	0x000000h 0x0001FEh 0x000200h 0x0007FEh 0x000800h 0x001FFEh 0x002000h 0x003FFEh 0x004000h 0x0057FEh
			BS = 768 IW		BS = 3840 IW		BS = 7936 IW	
	GS = 11008 IW		GS = 10240 IW		GS = 7168 IW		GS = 3072 IW	
		0x0157FEh		0x0157FEh		0x0157FEh		0x0157FEh

TABLE 28-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for Extended				
Param No.	Symbol	Characteristic	Min	Typ ⁽¹⁾	Max	Units	Conditions
DI60a	I _{ICL}	Input Low Injection Current	0	—	-5 ^(5,8)	mA	All pins except V _{DD} , V _{SS} , AV _{DD} , AV _{SS} , MCLR, VCAP, SOSC1, SOSCO, and RB14
DI60b	I _{ICH}	Input High Injection Current	0	—	+5 ^(6,7,8)	mA	All pins except V _{DD} , V _{SS} , AV _{DD} , AV _{SS} , MCLR, VCAP, SOSC1, SOSCO, RB14, and digital 5V-tolerant designated pins
DI60c	I _{ICT}	Total Input Injection Current (sum of all I/O and control pins)	-20 ⁽⁹⁾	—	+20 ⁽⁹⁾	mA	Absolute instantaneous sum of all $\pm$ input injection currents from all I/O pins (I _{ICL} + I _{ICH}) $\leq$ I _{ICT}

Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

- 2:** The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.
- 3:** Negative current is defined as current sourced by the pin.
- 4:** See “[Pin Diagrams](#)” for the 5V tolerant I/O pins.
- 5:** V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.
- 6:** Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.
- 7:** Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.
- 8:** Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.
- 9:** Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 28-6: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS

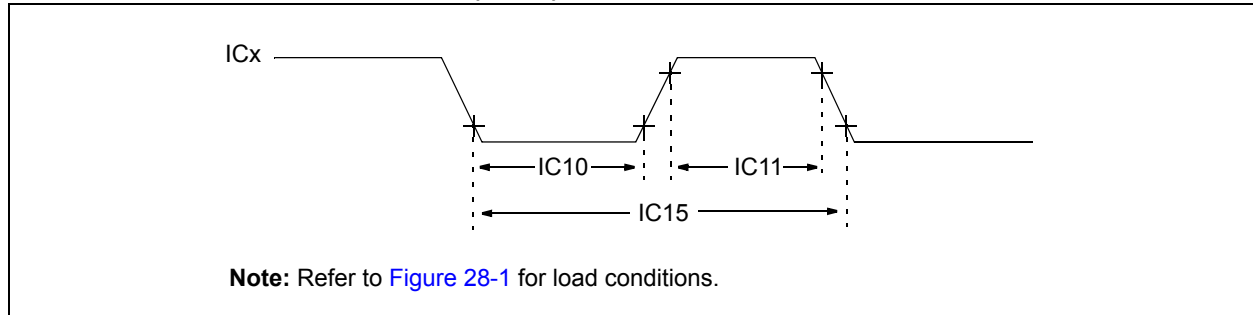


TABLE 28-25: INPUT CAPTURE TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	Symbol	Characteristic ⁽¹⁾		Min	Max	Units	Conditions
IC10	TccL	ICx Input Low Time	No Prescaler	0.5 Tcy + 20	—	ns	—
			With Prescaler	10	—	ns	
IC11	TccH	ICx Input High Time	No Prescaler	0.5 Tcy + 20	—	ns	—
			With Prescaler	10	—	ns	
IC15	TccP	ICx Input Period		(Tcy + 40)/N	—	ns	N = prescale value (1, 4, 16)

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 28-7: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS

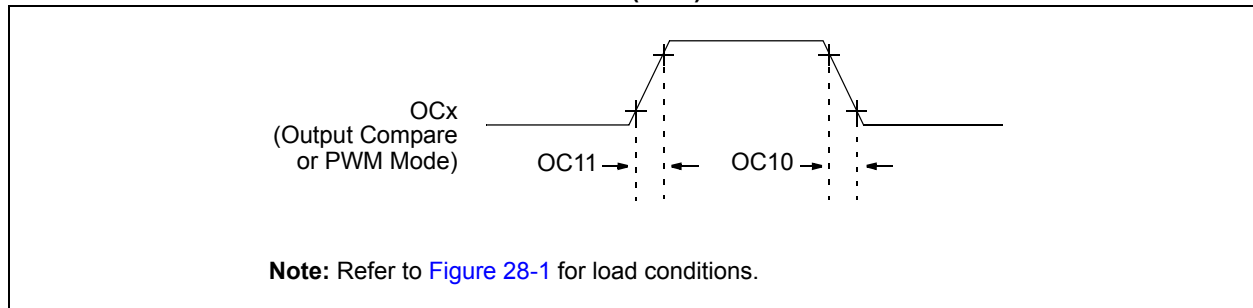


TABLE 28-26: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	Symbol	Characteristic ⁽¹⁾	Min	Typ	Max	Units	Conditions
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 28-36: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	Symbol	Characteristic		Min ⁽¹⁾	Max	Units	Conditions
IM10	TLO:SCL	Clock Low Time	100 kHz mode	Tcy/2 (BRG + 1)	—	μs	—
			400 kHz mode	Tcy/2 (BRG + 1)	—	μs	—
			1 MHz mode ⁽²⁾	Tcy/2 (BRG + 1)	—	μs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	Tcy/2 (BRG + 1)	—	μs	—
			400 kHz mode	Tcy/2 (BRG + 1)	—	μs	—
			1 MHz mode ⁽²⁾	Tcy/2 (BRG + 1)	—	μs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	Cb is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 Cb	300	ns	
			1 MHz mode ⁽²⁾	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	Cb is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 Cb	300	ns	
			1 MHz mode ⁽²⁾	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode ⁽²⁾	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	μs	—
			400 kHz mode	0	0.9	μs	
			1 MHz mode ⁽²⁾	0.2	—	μs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	Tcy/2 (BRG + 1)	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	Tcy/2 (BRG + 1)	—	μs	
			1 MHz mode ⁽²⁾	Tcy/2 (BRG + 1)	—	μs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	Tcy/2 (BRG + 1)	—	μs	After this period the first clock pulse is generated
			400 kHz mode	Tcy/2 (BRG + 1)	—	μs	
			1 MHz mode ⁽²⁾	Tcy/2 (BRG + 1)	—	μs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	Tcy/2 (BRG + 1)	—	μs	—
			400 kHz mode	Tcy/2 (BRG + 1)	—	μs	
			1 MHz mode ⁽²⁾	Tcy/2 (BRG + 1)	—	μs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	Tcy/2 (BRG + 1)	—	ns	—
			400 kHz mode	Tcy/2 (BRG + 1)	—	ns	
			1 MHz mode ⁽²⁾	Tcy/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	—
			400 kHz mode	—	1000	ns	—
			1 MHz mode ⁽²⁾	—	400	ns	—
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode ⁽²⁾	0.5	—	μs	
IM50	CB	Bus Capacitive Loading		—	400	pF	—
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	See Note 3

Note 1: BRG is the value of the I²C Baud Rate Generator. Refer to **Section 19. “Inter-Integrated Circuit (I²C™)”** (DS70235) in the “dsPIC33F/PIC24H Family Reference Manual”. Please see the Microchip web site (www.microchip.com) for the latest dsPIC33F/PIC24H Family Reference Manual chapters.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

29.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 AC characteristics and timing parameters for high temperature devices. However, all AC timing specifications in this section are the same as those in [Section 28.2 “AC Characteristics and Timing Parameters”](#), with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter OS53 in [Section 28.2 “AC Characteristics and Timing Parameters”](#) is the Industrial and Extended temperature equivalent of HOS53.

TABLE 29-8: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +150^{\circ}\text{C}$ for High Temperature Operating voltage V_{DD} range as described in Table 29-1 .
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FIGURE 29-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

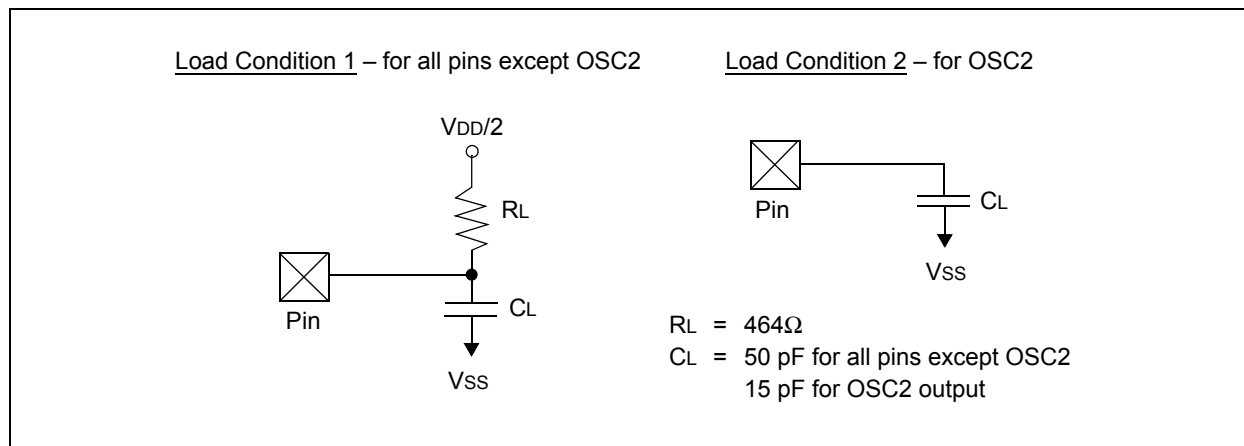
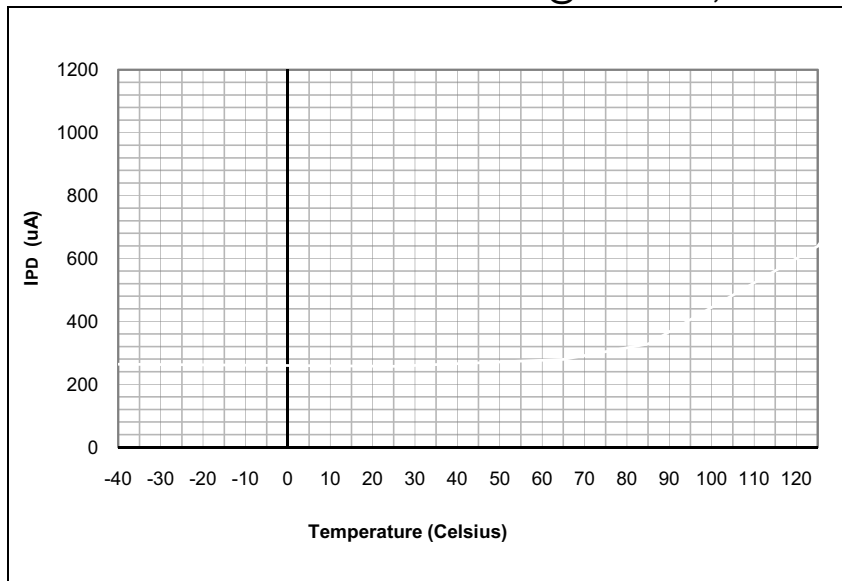
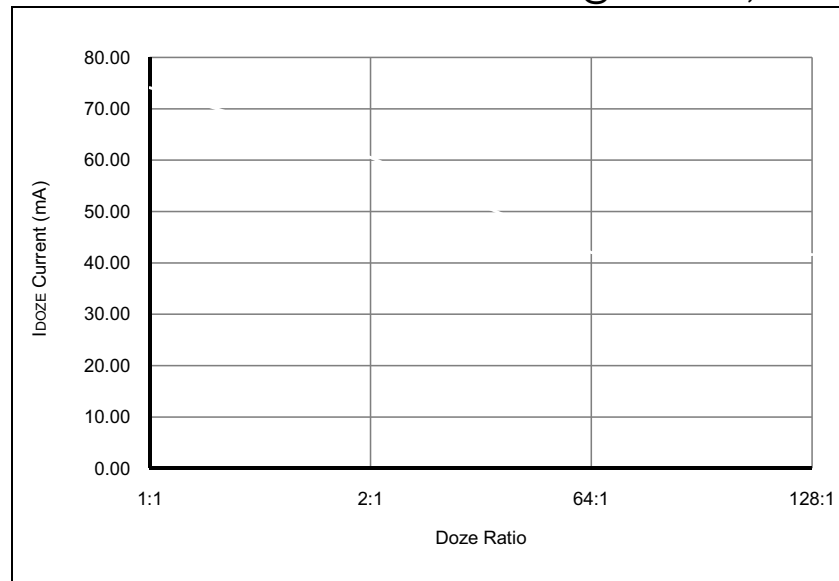
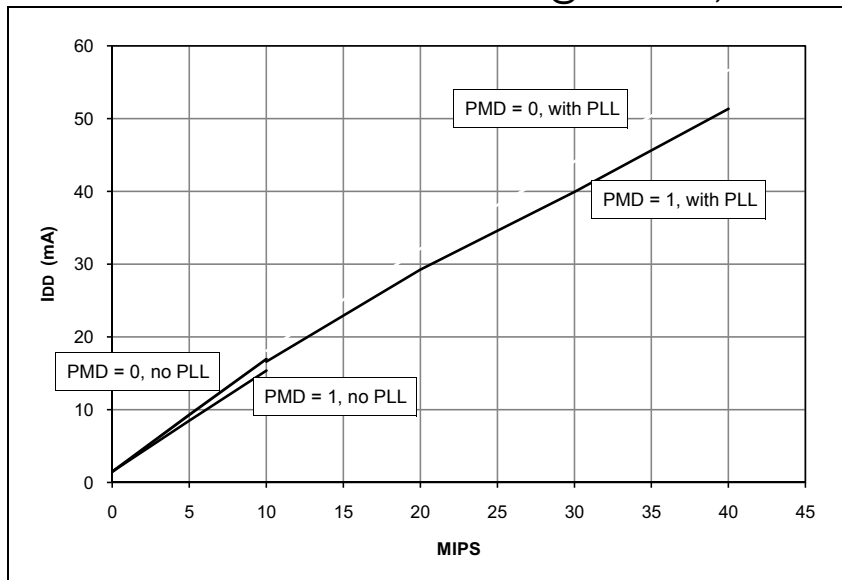
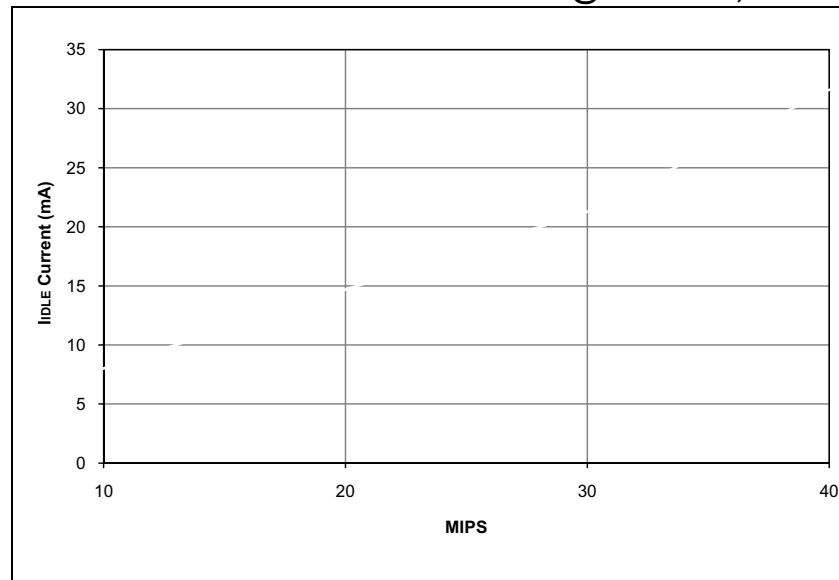


TABLE 29-9: PLL CLOCK TIMING SPECIFICATIONS

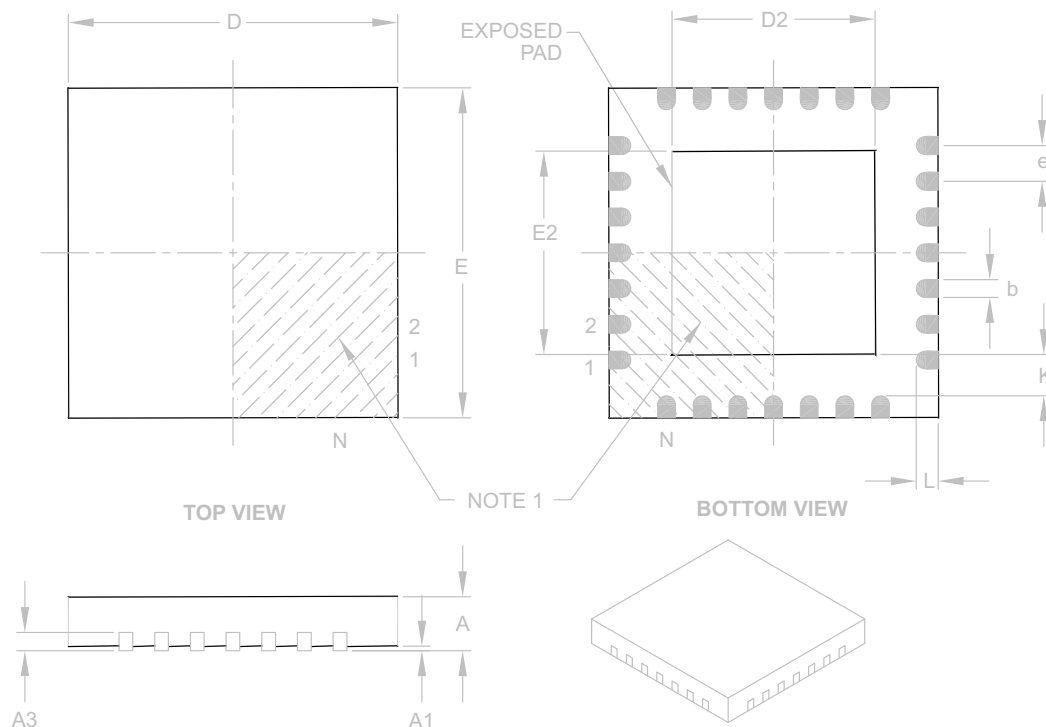
AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +150^{\circ}\text{C}$ for High Temperature					
Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
HOS53	DCLK	CLKO Stability (Jitter) ⁽¹⁾	-5	0.5	5	%	Measured over 100 ms period

Note 1: These parameters are characterized, but are not tested in manufacturing.

FIGURE 32-9: TYPICAL I_{PD} CURRENT @ $V_{DD} = 3.3V$, $+85^{\circ}C$ **FIGURE 32-11: TYPICAL I_{DOZE} CURRENT @ $V_{DD} = 3.3V$, $+85^{\circ}C$** **FIGURE 32-10: TYPICAL I_{DD} CURRENT @ $V_{DD} = 3.3V$, $+85^{\circ}C$** **FIGURE 32-12: TYPICAL I_{IDLE} CURRENT @ $V_{DD} = 3.3V$, $+85^{\circ}C$** 

**28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S]
with 0.40 mm Contact Length**

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		28		
Pitch	e		0.65 BSC		
Overall Height	A		0.80	0.90	1.00
Standoff	A1		0.00	0.02	0.05
Contact Thickness	A3		0.20 REF		
Overall Width	E		6.00 BSC		
Exposed Pad Width	E2		3.65	3.70	4.70
Overall Length	D		6.00 BSC		
Exposed Pad Length	D2		3.65	3.70	4.70
Contact Width	b		0.23	0.38	0.43
Contact Length	L		0.30	0.40	0.50
Contact-to-Exposed Pad	K		0.20	–	–

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-124B

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